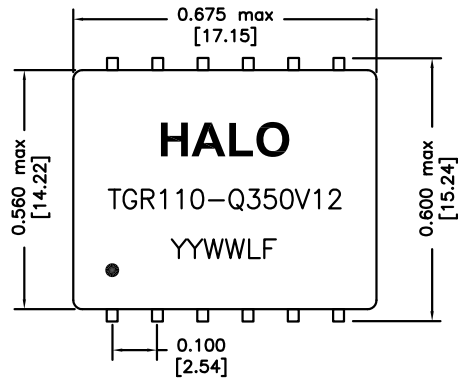
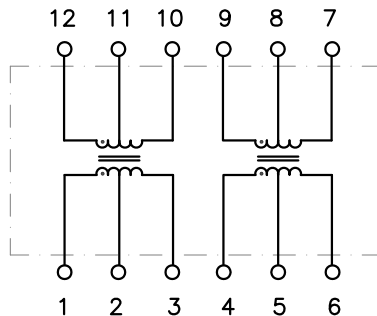


DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



PART NO. : TGR110-Q350V12LF

12PIN SMT ISOLATION MODULE

DESIGNED FOR FAST ETHERNET APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

COMPLIANT TO UL60950 REINFORCED INSULATION
REQUIREMENTS FOR WORKING VOLTAGE UP TO 300V

DUAL-LAYER INSULATION FROM WINDINGS TO CORE

MAT'L GROUP I, 5mm CLEARANCE/8mm CREEPAGE DIST.

EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @ 25°C

URNS RATIO

P1-3:P12-10

1CT:1CT ±3%

P4-6:P9-7

1CT:1CT ±3%

OCL (100KHz,0.1Vrms,8mA)

P1-3,P4-6

350µH min

DCR P1-3,P4-6

0.9Ω max

LL P1-3,P4-6

0.8µH max

Cw/w

15pF max

CROSSTALK 1-100MHz

-40dB typ

ISOLATION

4,500Vrms/60 sec

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE TRANSFORMER MODULE

FOR FAST ETHERNET

PART NO. TGR110-Q350V12LF

SCALE NONE

PAGE 1 OF 2

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE Q350V12LF.DWG

DATE

10/2/13

2/8/16

2/8/16

REV.

A

B

C

DESC.

FIRST ISSUE

UPDATE

PROD. RELEASE

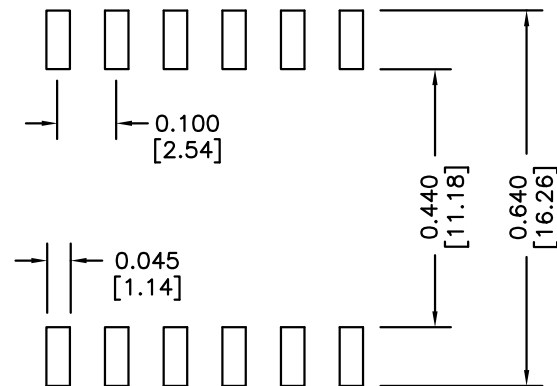
DATE

10/2/13

1/29/15

2/8/16





RECOMMENDED SOLDER PAD DIMENSIONS
 DIMENSIONS: INCH [mm]

HALO/PBL CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE	TITLE TRANSFORMER MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR FAST ETHERNET		DRAWN LI ZHI ZHONG		10/2/13	A	FIRST ISSUE	10/2/13
	PART NO. TGR110-Q350V12LF		CHECKED LEI KEONG		2/8/16	B	UPDATE	1/29/15
	SCALE NONE		APPROVED PETER LU		2/8/16	C	PROD. RELEASE	2/8/16
	PAGE 2 OF 2		FILE Q350V12LF.DWG					